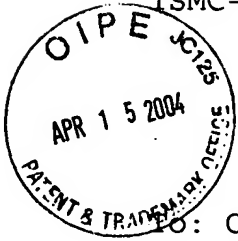


TSMC-02-181



April 9, 2004

To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/782,365 02/19/04 |
Hsin-Ching Shih et al.
SEAL RING DESIGN WITHOUT STOP LAYER
PUNCH THROUGH DURING VIA ETCH
| _____ |

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on April 12, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

SB Ackerman 4/12/04

U.S. Patent 5,723,385 to Shen et al., "Wafer Edge Seal Ring Structure," discusses a wafer edge seal ring for reduced particle and contaminant generation during wafer processing.

U.S. Patent 6,362,524 to Blish et al., "Edge Seal Ring for Copper Damascene Process and Method for Fabrication Thereof," reveals an edge seal ring for a copper damascene process.

U.S. Patent 5,891,808 to Chang et al., "Method for Fabricating a Die Seal," teaches a seal ring process and an etch stop.

U.S. Patent 6,300,223 to Chang et al., "Method of Forming Die Seal Structures Having Substrate Trenches," discusses a seal ring process.

Sincerely,

A handwritten signature in black ink, appearing to be 'SBA', written over the printed name.

Stephen B. Ackerman,
Reg. No. 37761

Form PTO-1449

Docket Number (Optional)

Application Number

TSMC-02-181

10/782,365

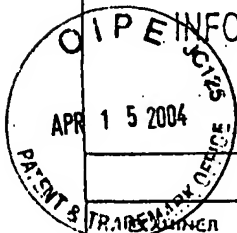
Applicant

Hsin-Ching Shih et al.

Filing Date

02/19/04

Draw Art Unit



INFORMATION DISCLOSURE CITATION IN AN APPLICATION

(Use several sheets if necessary)

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	TITLE	CLASS	SUBCLASS	FILED DATE & APPROXIMATE
	5723385	3/3/98	Shen et al.	438	763	12/16/96
	6362524	3/26/02	Blish et al.	257	734	7/26/00
	5891808	4/6/99	Chang et al.	438	740	6/6/97
	6300223	10/9/01	Chang et al.	438	460	3/28/97

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Portion of Pages, Etc.)

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.